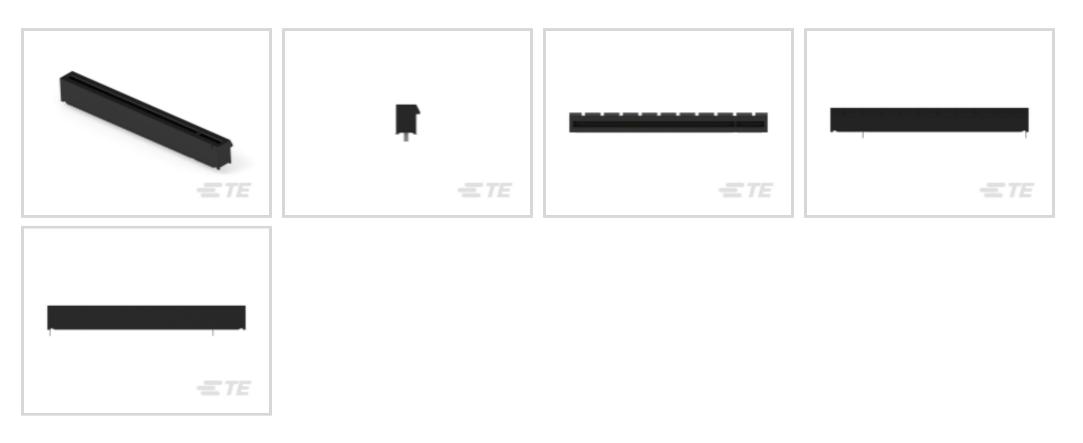
2-2388957-4 - ACTIVE

TE Internal #: 2-2388957-4 PCI & PCI Express Connectors, Board-to-Board, 164 Position, .04 in [1 mm] Centerline, Vertical, Black, Height 11.25 mm [.44 in], Width 8.2 mm [.32 in]

### View on TE.com >



Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



Connector System: Board-to-Board

Number of Positions: 164

PCI Generation: 5

Centerline (Pitch): 1 mm [.04 in ]

Termination Post & Tail Length: 1.1 mm [.043 in ]

### Features

### Product Type Features

Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	164
PCB Mount Orientation	Vertical
Ejector	Without
Contact Features	
	30 µin
Contact Current Rating (Max)	1.1 A
Termination Features	
Termination Method to Printed Circuit Board	Surface Mount
Termination Post & Tail Length	1.1 mm[.043 in]
Mechanical Attachment	

**C** For support call+1 800 522 6752

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PCI & PCI Express Connectors, Board-to-Board, 164 Position, .04 in [1 mm] Centerline, Vertical, Black, Height 11.25 mm [.44 in], Width 8.2 mm [.32 in]



PCB Mount Retention Type	Tab
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1 mm[.04 in]
Housing Color	Black
Dimensions	
Connector Height	11.25 mm[.44 in]
Connector Width	8.2 mm[.32 in]
Usage Conditions	
Operating Temperature Range	-40 – 85 °C[-40 – 185 °F]
Operation/Application	
Circuit Application	High Speed Data
Industry Standards	
PCI Generation	5

### **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Soldar Process Canability	Not reviewed for colder process capability

Solder Process Capability

Not reviewed for solder process capability

### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits

### 2-2388957-4

PCI & PCI Express Connectors, Board-to-Board, 164 Position, .04 in [1 mm] Centerline, Vertical, Black, Height 11.25 mm [.44 in], Width 8.2 mm [.32 in]



as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

# **Compatible Parts**



## Documents

Product Drawings PCIE5,SMT,2X2.76TAB,164P,30",WO ML,HT

English

### **CAD** Files

Customer View Model ENG\_CVM\_CVM\_2-2388957-4\_A.3d\_igs.zip

English

**Customer View Model** 

### ENG\_CVM\_CVM\_2-2388957-4\_A.3d\_stp.zip

English

Customer View Model ENG\_CVM\_CVM\_2-2388957-4\_A.2d\_dxf.zip

English

3D PDF

3D

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English